

Day 1 - Monday 20th April 2026

- 11:00 AngelTech Innovate Summit - Limited places! Requires separate registration: <https://www.angeltech-innovate.net/register>
- 18:00 Pre-conference Networking Drinks / Dinner Reception (available to those who have registered for 21st & 22nd April for AngelTech Conference)

Day 2 - Tuesday 21st April 2026

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebbby and David Cheskis - Conference Chairs

Foundations of PIC design: materials, devices and processes

- 09:00 **Scaling Co-packaged Optics Requires a Fundamental Rethink of Fibre-to-chip Interconnects**
Presented by Dominic Sulway - Light Trace Photonics
- 09:15 **Advances in PIC Testing: Challenges and Measurement Needs from R&D to Volume Production**
Presented by Marc-Andre Laliberte - APEX Technologies
- 09:30 **From Design to Silicon: Foundry Solutions for Next-Gen Photonics ICs**
Presented by Bowen Wang - Tower Semiconductor
- 09:45 **Simulation-Driven PIC Design – Accelerating Performance, Reliability and Time-to-Market**
Presented by Shin-Sung Kim - Ansys, part of Synopsys
- 10:00 **Photonics Chip Level Test Strategies Overcoming Vibration Challenges in High Volume Production Environments**
Presented by Nikta Jalayer - Physik
- 10:15 **Glass-Integrated PICs: Shaping the Future of Photonics**
Presented by Giacomo Corrielli - Ephos
- 10:30 **Enabling High-Volume PIC Manufacturing through Interactive Verification & Data-Driven Design Workflows**
Presented by Martin Fiers - Luceda Photonics

10:45 Morning Break and Networking

- 11:15 **High Yield, High Volume TFLN Technology Using CMOS Compatible Processing**
Presented by Bob van Someren - Rapid Photonics
- 11:30 **LN-Based PICs: Novel Techniques for Structuring and Yield Improvements with Ion Beam Etching**
Presented by Susanne Hartmann - scia Systems GmbH
- 11:45 **New Materials for Enabling High-performance Photonic Devices and Emerging Applications**
Presented by Leili Shiramin - imec
- 12:00 **TFLN for CPO and Beyond**
Presented by Hiroyuki Takanashi - Shincron Co. Ltd
- 12:15 **How Co Packaged Optics Is Transforming Optical Test & Measurement**
Presented by Matt Adams - VIAVI Solutions
- 12:30 **Next-Generation Ultra-Low-Loss Integrated Photonics: From Mode-Locked Lasers to Traveling-Wave Amplifiers**
Presented by Tobias Kippenberg - Swiss Federal Institute of Technology (EPFL)

12:45 Lunch Break and Networking

14:15 Startup Elevator Presentations

Connectivity and scalability for secure, high-speed data networks

Sponsored by OPTICA

- 14:25 **PIC-enabled Quantum-safe Cryptography**
Presented by Francesco Raffaelli - KETS Quantum Security
- 14:40 **Building Scalable, Energy-Efficient TFLN PICs Through Industrial-Grade Manufacturing**
Presented by Hernán Furci - CCRAFT
- 14:55 **Beyond the Chip: System-Scale Simulations for Next-Gen PICs**
Presented by Andrzej Pożatynski - VPIphotonics
- 15:10 **Optics in AI Clusters: Innovation Mixed with Expediency**
Presented by Roy Rubenstein - LightCounting
- 15:25 Afternoon Break and Networking
- 15:55 **Integrated Optics in the Age of AI**
Presented by Jochem Verbist - NVIDIA
- 16:10 **Integrated Photonics from Opportunity to Mass Production for 50G+ Access Networks**
Presented by Antonio Teixeira - PICadvanced
- 16:25 **Enabling Network Scalability through Advanced Photonic Integration**
Presented by Mehrdad Ziari - Nokia
- 16:40 **Silicon Photonics Platform for Next-Generation Co-Packaged Optics and Optical I/O**
Presented by Yoojin Ban - imec
- 16:55 **From Lab to Volume: Scalable Active Alignment & Test Automation for PIC-Based Optical Transceivers**
Presented by Tobias Müller - Aixemtec
- 17:10 **Novel Startups in Photonic Integrated Circuits — From Concept to Deployment**
Light Trace Photonics, KETS Quantum Security, InSpek, Alter Technology, and Uviquity
- 17:40 Closing Remarks

18:00 **Networking Drinks and Dinner Reception (concludes around 20:00)**

18:30 **AngelTech Rump Session - Bottlenecks & Battlegrounds: The Future of the AI Chip Ecosystem**
Presented by David Cheskis - Square Zero Technologies, and Diana Khlan - Chips Weekly

Day 3 - Wednesday 22nd April 2026

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebby and David Cheskis - Conference Chairs

Future computing: PICs for photonic processing, quantum computers, and neural networks

09:00 **PIC for Photonic Quantum Computing**

Presented by Nicolas Maring - Quandela

09:15 **System-Level Simulation: Towards Hardware-Software Co-Design for Photonics-Enabled AI Accelerators**

Presented by Sébastien d'Herbais de Thun - Hewlett Packard Enterprise

09:30 **Beyond Electronics with TFLN Photonic Integrated Circuits for Next-Generation Computing**

Presented by Sep Mohajerani - Quantum Computing Inc

09:45 **AIM Photonics / NY Creates PIC and Packaging Foundry for an End-to-End Approach to the Challenges in Photonic Integrated Circuits (PIC) and Packaging**

Presented by David Harame - AIM Photonics

10:00 Morning Break and Networking

Foundations of PIC design: materials, devices and processes

10:30 **Enabling THz Bandwidth on-chip with Plasmonic Modulators**

Presented by Stephan Koch - Polariton Technologies AG

10:45 **Advancing Scalable Photonic Integration: Heterogeneous Integration of Active Components for Next-Generation Applications**

Presented by Michael Geiselmann - LIGENEC

11:00 **Aligned 2-Photon Grayscale Lithography for Free Space Microoptical Coupling in Photonic Packaging**

Presented by Stephan Dottermusch - Nanoscribe

11:15 **How Photonic Intelligent Manufacturing Enables Artificial Intelligence at Scale**

Presented by Lorenzo Mandelli - ficonTEC

11:30 **Scaling Integrated Photonics by Advancing Wafer Uniformity via Vacuum Technologies**

Presented by Daniel de Sá Pereira - Buhler Group

11:45 **Enabling Scalable Silicon Photonics Manufacturing Through Laser-Based Trimming and Cleaning**

Presented by Simon Duval - Femtum

12:00 **Convergence of Photonics and Electronics in Design**

Presented by Xu Wang - Cadence

12:15 **From Materials to Silicon Photonics PDKs: Scaling Foundry Platforms to 400G and Beyond**

Presented by Robert Blum - Lightwave Logic

12:30 Lunch Break and Networking

Connectivity and scalability for secure, high-speed data networks

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13:45 **Designing for Yield: Production-Grade PDKs for Ultra-high-speed TFLN Photonic Engines**

Presented by Amir Ghadimi - Lightium

14:00 **Building the Fab of the Future: Scaling PIC Manufacturing Through Ecosystem Collaboration**

Presented by Andre van de Geijn - Smart Photonics, and Bart Thiesen - Itility

14:15 **Advancing Photonic Packaging and Integration Through UV Nanoimprint Lithography**

Presented by Patrick Schuster - EV Group

14:30 **Industry Ready Photonic Integration using Photonic Wire Bonds and Facet-Attached Micro-Lenses**

Presented by Abdeslem Ben Hamida - Vanguard Automation

14:45 **Photonic Integrated Circuits and Co-packaged Optics for HPC and AI Data Centers**

Presented by Mika Takahashi - IDTechEx

15:00 Afternoon Break and Networking

Emerging applications: photonics for sensing, imaging and beyond

Sponsored by UpNano GmbH

15:30 **From Fab to Solving Real-World Challenges: Delivering 11 Real-World Proof Points by 2029**

Presented by Peter van Arkel - PhotonDelta

15:45 **Enabling Foundry Ready BaTiO₃ Photonics: Advances and 300 mm Wafer Manufacturing**

Presented by Sabina Hatch - DCA Instruments

16:00 **All Glass Atomic-photonic Chips for Quantum Sensing and Metrology**

Presented by Gianvito Lucivero - University of Bari/QSensAto

16:15 **Multi-Wavelength Laser Sources for Scaling Datacenter Capacity**

Presented by Amol Delmade - Pilot Photonics

16:30 **Aluminum Nitride Photonic Integrated Circuits for Extending Nonlinear Photonics Applications to UV Spectrum**

Presented by Scott Burroughs - Uviquity

